

Dual-Channel, 250-MSPS Feedback Receiver IC

Check for Samples: [ADS62PF49](#)

FEATURES

- **Maximum Output Sample Rate: 250 MSPS**
- **Pin-Compatible with [ADS62P49](#)**
- **Variable Output Resolution**
 - **High Resolution Burst Mode with 14-Bit Output: 73 dB SNR at Low IF, 70.5 dB SNR at 170 MHz**
 - **Low Resolution with 9-Bit 250 MSPS or 11-Bit 125 MSPS**
- **Double Data Rate (DDR) LVDS Output**
- **Programmable Gain up to 6 dB for SNR/SFDR Trade-off**
- **90-dB Cross-Talk**
- **Power Consumption of 1.25 W**
- **64-Pin QFN Package (9 mm × 9 mm)**

APPLICATIONS

- **Feedpath Path for Multi-Carrier, Multi-Mode Cellular Infrastructure Base Stations**

DESCRIPTION

The ADS62PF49 is a dual-channel feedback receiver IC with sampling rates up to 250 MSPS. It allows a high-resolution, 14-bit output for a limited time followed by a low-resolution mode with a minimum of 8x longer time. It is pin-compatible to the ADS62P49 and ADS62C17 dual ADCs.

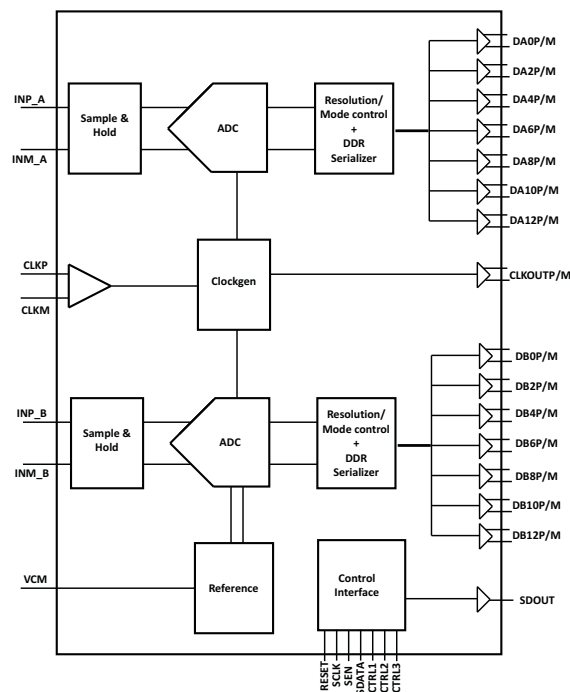
The ADS62PF49 has gain options that can be used to improve SFDR performance at lower full-scale input ranges. It includes a dc offset correction loop that can be used to cancel the analog-to-digital conversion (ADC) offset.

It includes internal references while the traditional reference pins and associated decoupling capacitors have been eliminated. The device is specified over the industrial temperature range (–40°C to 85°C).

Table 1. Performance Summary

AT 170-MHz INPUT		PERFORMANCE IN HIGH-RESOLUTION MODE
SFDR, dBc	0-dB gain	75
	6-dB gain	82
SINAD, dBFS	0-dB gain	69.8
	6-dB gain	66.5

ADS62PF49 Block Diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
ADS62PF49IRGCR	ACTIVE	VQFN	RGC	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
ADS62PF49IRGCT	ACTIVE	VQFN	RGC	64	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS62PF49IRGCR	VQFN	RGC	64	2000	330.0	16.4	9.3	9.3	1.5	12.0	16.0	Q2
ADS62PF49IRGCT	VQFN	RGC	64	250	330.0	16.4	9.3	9.3	1.5	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS62PF49IRGCR	VQFN	RGC	64	2000	336.6	336.6	28.6
ADS62PF49IRGCT	VQFN	RGC	64	250	336.6	336.6	28.6

MECHANICAL DATA

RGC(S-PVQFN-N64) CUSTOM DEVICE PLASTIC QUAD FLATPACK NO-LEAD



4204106/F 11/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994.
 - This drawing is subject to change without notice.
 - Quad Flatpack, No-leads (QFN) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

THERMAL PAD MECHANICAL DATA

RGC (S-PVQFN-N64)

PLASTIC QUAD FLATPACK NO-LEAD

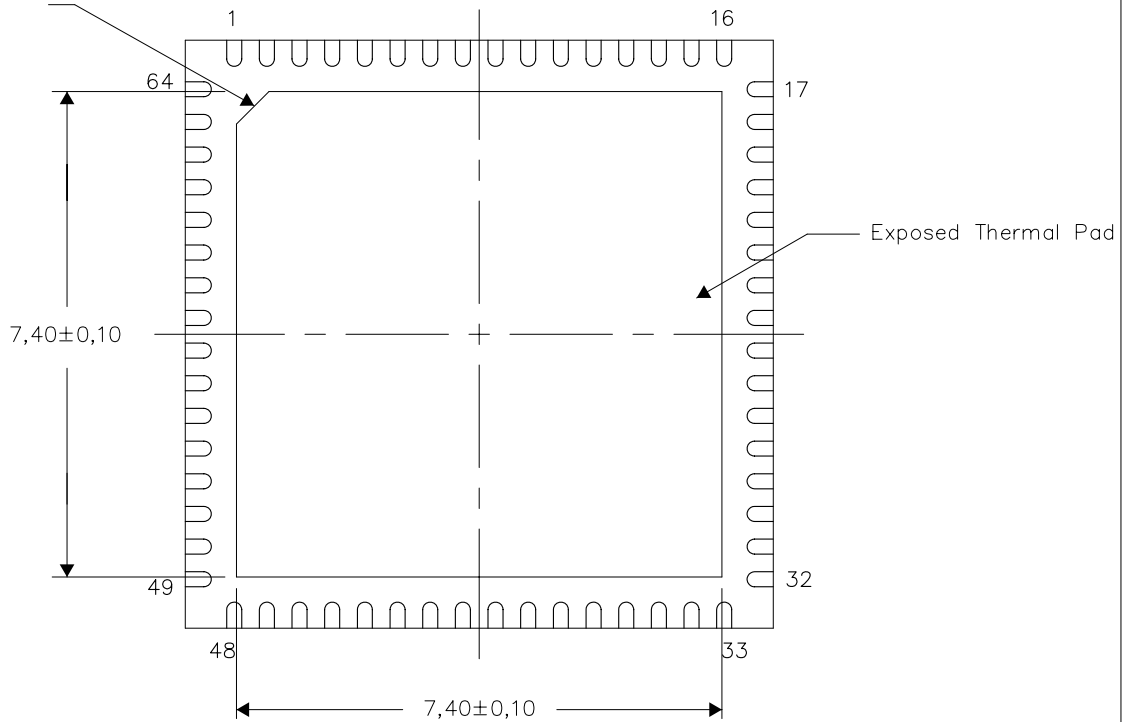
THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

PIN 1 INDICATOR
CO,35



Bottom View

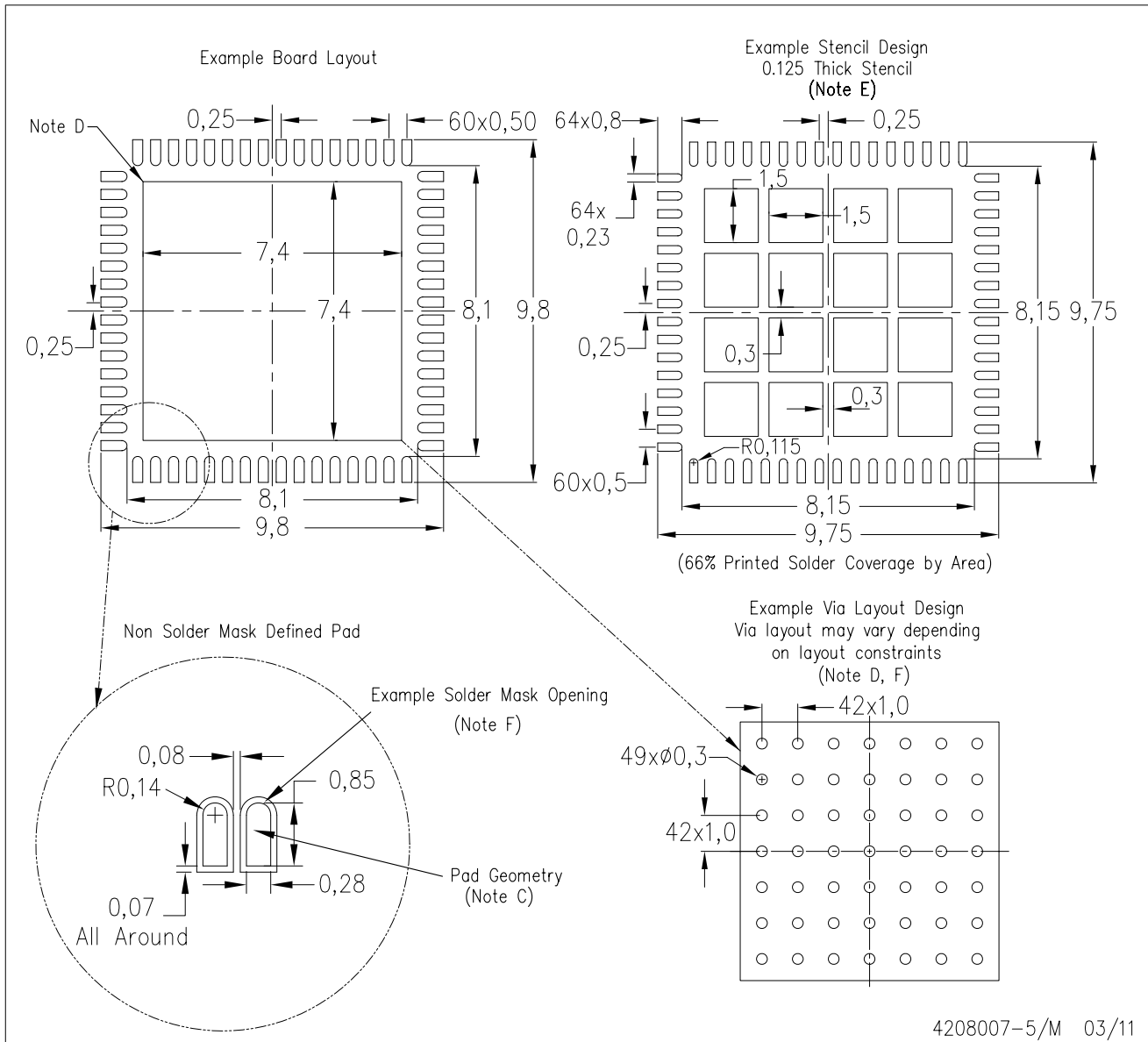
Exposed Thermal Pad Dimensions

4206192-4/P 01/12

NOTE: A. All linear dimensions are in millimeters

RGC (S-PVQFN-N64)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in thermal pad.

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